

- **Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs**

description

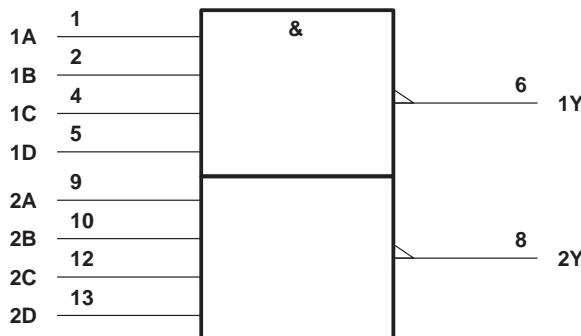
These devices contain two independent 4-input positive-NAND gates. They perform the Boolean functions $Y = A \bullet B \bullet C \bullet D$ or $Y = \bar{A} + \bar{B} + \bar{C} + \bar{D}$ in positive logic.

The SN54ALS20A and SN54AS20 are characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALS20A and SN74AS20 are characterized for operation from 0°C to 70°C .

FUNCTION TABLE
(each gate)

INPUTS				OUTPUT Y
A	B	C	D	
H	H	H	H	L
L	X	X	X	H
X	L	X	X	H
X	X	L	X	H
X	X	X	L	H

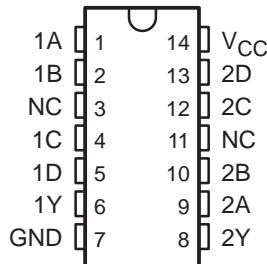
logic symbol†



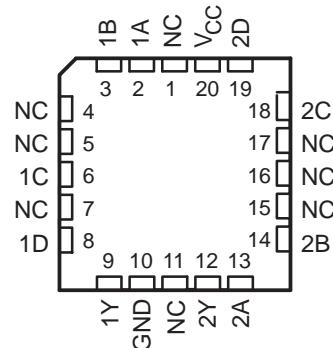
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

SN54ALS20A, SN54AS20 . . . J PACKAGE
SN74ALS20A, SN74AS20 . . . D OR N PACKAGE
(TOP VIEW)

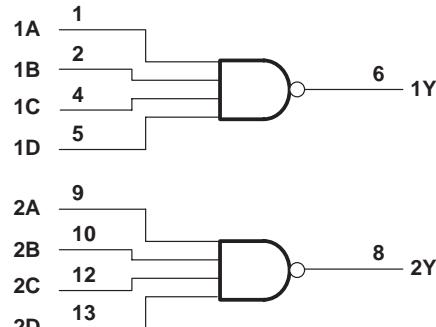


SN54ALS20A, SN54AS20 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

logic diagram (positive logic)



SN54ALS20A, SN54AS20, SN74ALS20A, SN74AS20 DUAL 4-INPUT POSITIVE-NAND GATES

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54ALS20A			SN74ALS20A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage		0.8 [†]			0.8		V
			0.7 [§]					
I _{OH}	High-level output current			-0.4			-0.4	mA
I _{OL}	Low-level output current			4			8	mA
T _A	Operating free-air temperature	-55		125	0		70	°C

† Applies over temperature range -55°C to 70°C

§ Applies over temperature range 70°C to 125°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54ALS20A			SN74ALS20A			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA			-1.5			-1.5	V
V _{OH}	V _{CC} = 4.5 V to 5.5 V, I _{OH} = -0.4 mA		V _{CC} - 2		V _{CC} - 2			V
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 4 mA		0.25	0.4		0.25	0.4
		I _{OL} = 8 mA					0.35	0.5
I _I	V _{CC} = 5.5 V, V _I = 7 V			0.1			0.1	mA
I _{IH}	V _{CC} = 5.5 V, V _I = 2.7 V			20			20	µA
I _{IL}	V _{CC} = 5.5 V, V _I = 0.4 V			-0.1			-0.1	mA
I _{O[#]}	V _{CC} = 5.5 V, V _O = 2.25 V	-20	-112		-30	-112		mA
I _{CCH}	V _{CC} = 5.5 V, V _I = 0		0.22	0.4		0.22	0.4	mA
I _{CCL}	V _{CC} = 5.5 V, V _I = 4.5 V		0.81	1.5		0.81	1.5	mA

All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{SC} .

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$, $C_L = 50 \text{ pF}$, $R_L = 500 \Omega$, $T_A = \text{MIN to MAX}^{\dagger}$				UNIT	
			SN54ALS20A		SN74ALS20A			
			MIN	MAX	MIN	MAX		
t_{PLH}	A, B, C, or D	Y	1	12.5	3	11	ns	
t_{PHL}			1	11	3	10		

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Operating free-air temperature range, T_A : SN54AS20	-55°C to 125°C
SN74AS20	0°C to 70°C
Storage temperature range	-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54AS20			SN74AS20			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			-2			-2	mA
I_{OL}	Low-level output current			20			20	mA
T_A	Operating free-air temperature	-55	125	0	0	70	0	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54AS20			SN74AS20			UNIT
		MIN	TYP [§]	MAX	MIN	TYP [§]	MAX	
V_{IK}	$V_{CC} = 4.5 \text{ V}$, $I_I = -18 \text{ mA}$			-1.2			-1.2	V
V_{OH}	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$, $I_{OH} = -2 \text{ mA}$	$V_{CC} - 2$			$V_{CC} - 2$			V
V_{OL}	$V_{CC} = 4.5 \text{ V}$, $I_{OL} = 20 \text{ mA}$	0.35	0.5		0.35	0.5		V
I_I	$V_{CC} = 5.5 \text{ V}$, $V_I = 7 \text{ V}$			0.1			0.1	mA
I_{IH}	$V_{CC} = 5.5 \text{ V}$, $V_I = 2.7 \text{ V}$			20			20	μA
I_{IL}	$V_{CC} = 5.5 \text{ V}$, $V_I = 0.4 \text{ V}$			-0.5			-0.5	mA
I_O^{\dagger}	$V_{CC} = 5.5 \text{ V}$, $V_O = 2.25 \text{ V}$	-30	-112		-30	-112		mA
I_{CCH}	$V_{CC} = 5.5 \text{ V}$, $V_I = 0$	1	1.6		1	1.6		mA
I_{CCL}	$V_{CC} = 5.5 \text{ V}$, $V_I = 4.5 \text{ V}$	5.4	8.7		5.4	8.7		mA

[§] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.

[¶] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

SN54ALS20A, SN54AS20, SN74ALS20A, SN74AS20
DUAL 4-INPUT POSITIVE-NAND GATES

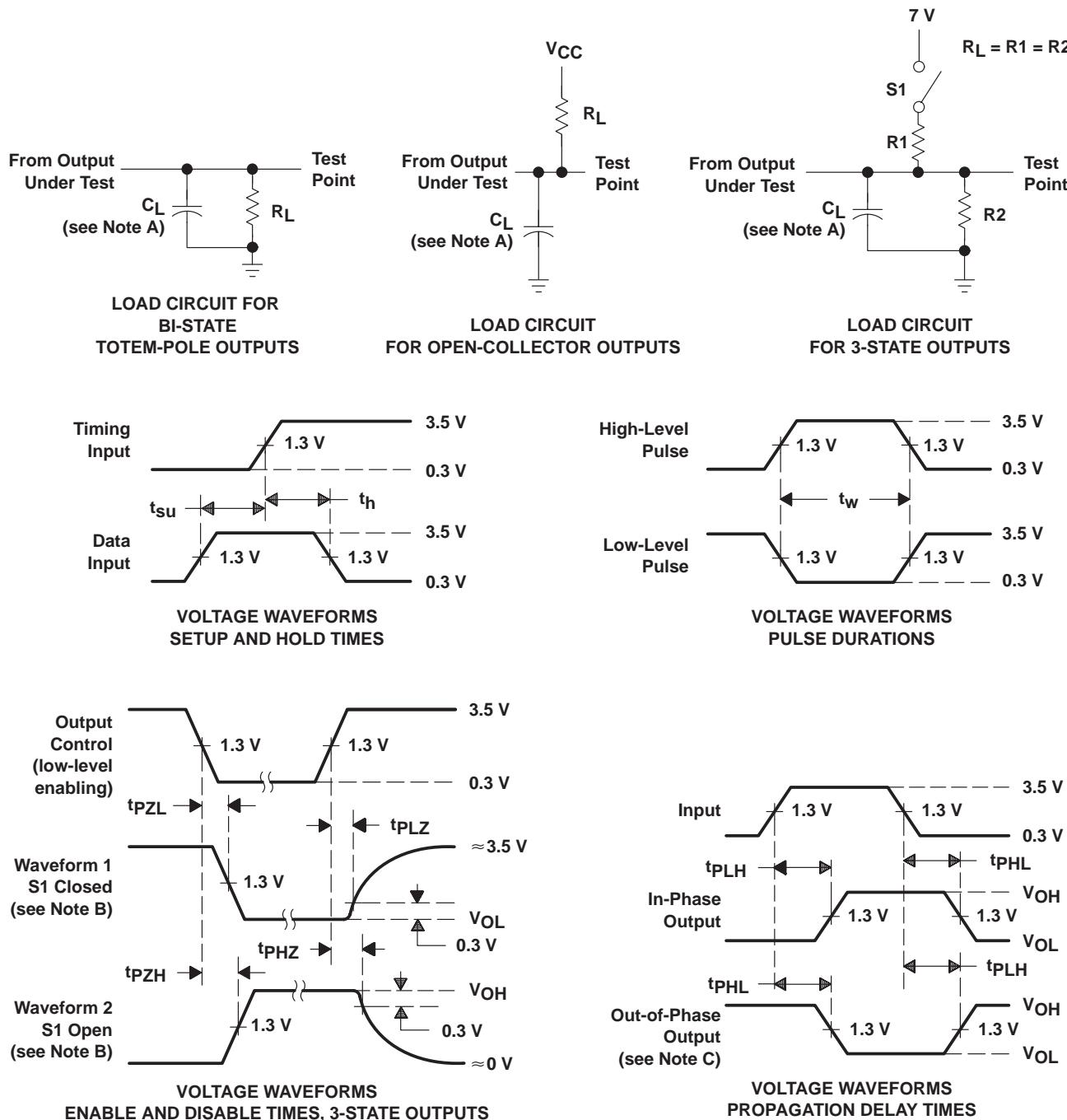
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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$, $C_L = 50 \text{ pF}$, $R_L = 500 \Omega$, $T_A = \text{MIN to MAX}^\dagger$				UNIT	
			SN54AS20		SN74AS20			
			MIN	MAX	MIN	MAX		
t_{PLH}	A, B, C, or D	Y	1	5.5	1	5	ns	
			1	5	1	4.5		

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES:

- C_L includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- When measuring propagation delay items of 3-state outputs, switch S1 is open.
- All input pulses have the following characteristics: PRR \leq 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
- The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-8858901DA	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type
JM38510/37003B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	N / A for Pkg Type
JM38510/37003BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type
SN54ALS20AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type
SN54AS20J	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type
SN74ALS20AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS20ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS20ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS20ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS20ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS20ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS20AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS20ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS20ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS20ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS20D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS20DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS20DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS20DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS20N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS20NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS20NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS20NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ALS20AFK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	N / A for Pkg Type
SNJ54ALS20AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type
SNJ54ALS20AW	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type
SNJ54AS20FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	N / A for Pkg Type
SNJ54AS20J	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

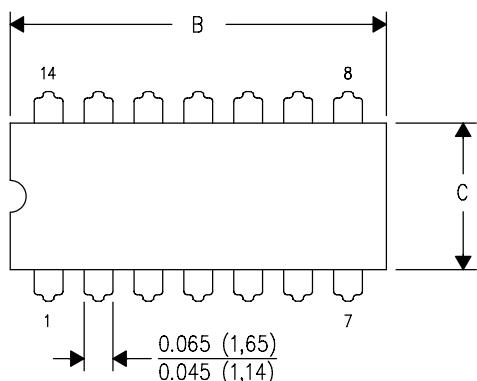
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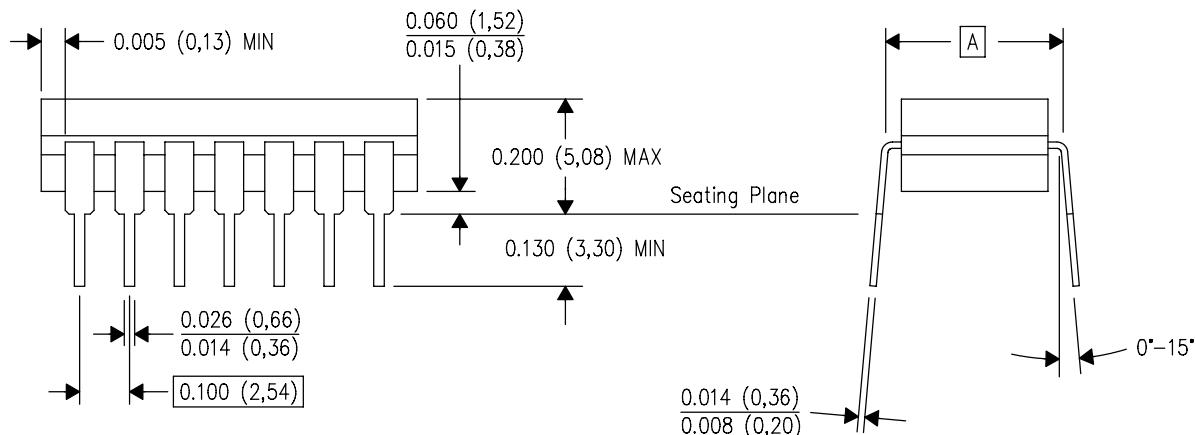
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

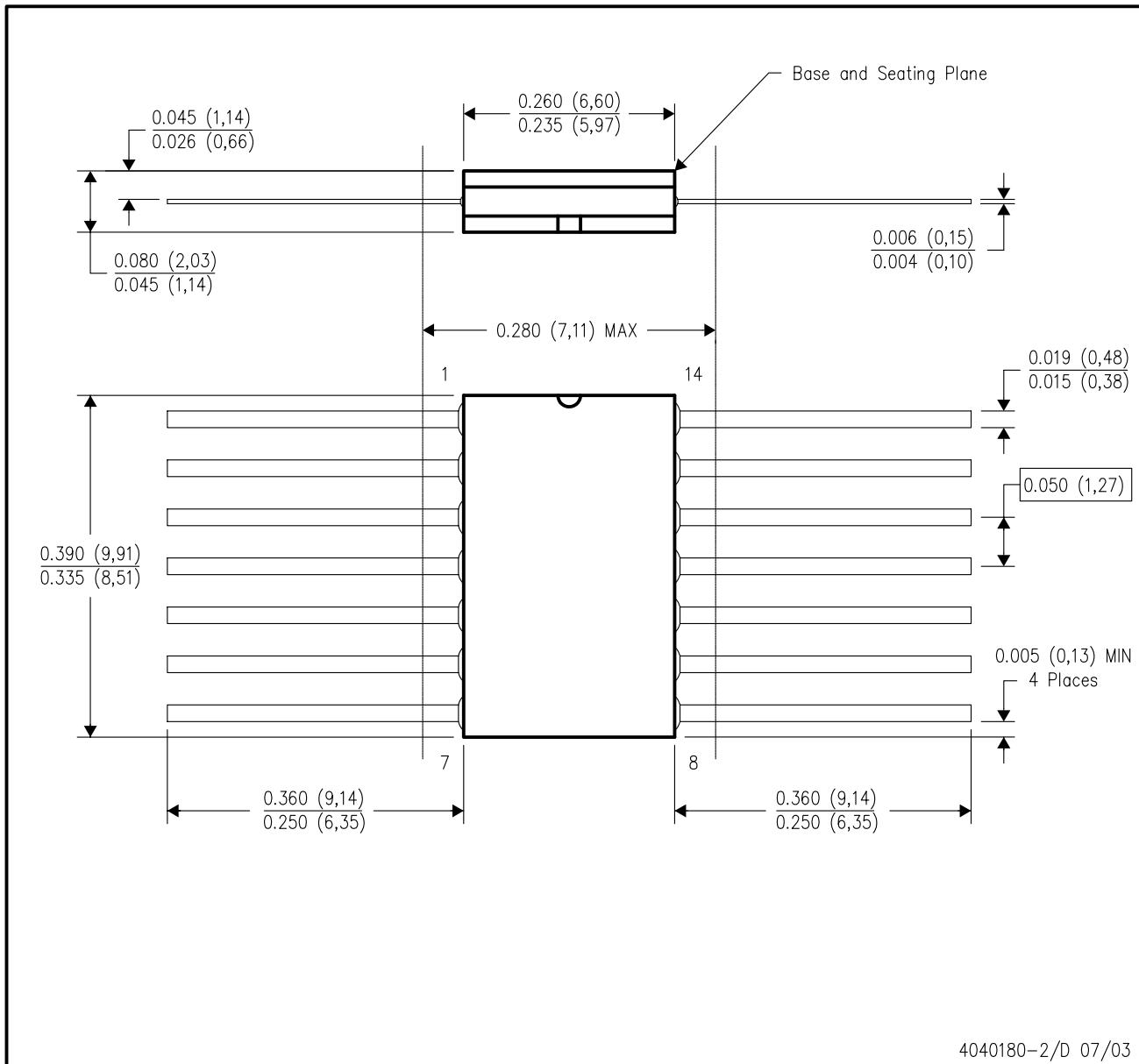


4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within MIL-STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES:

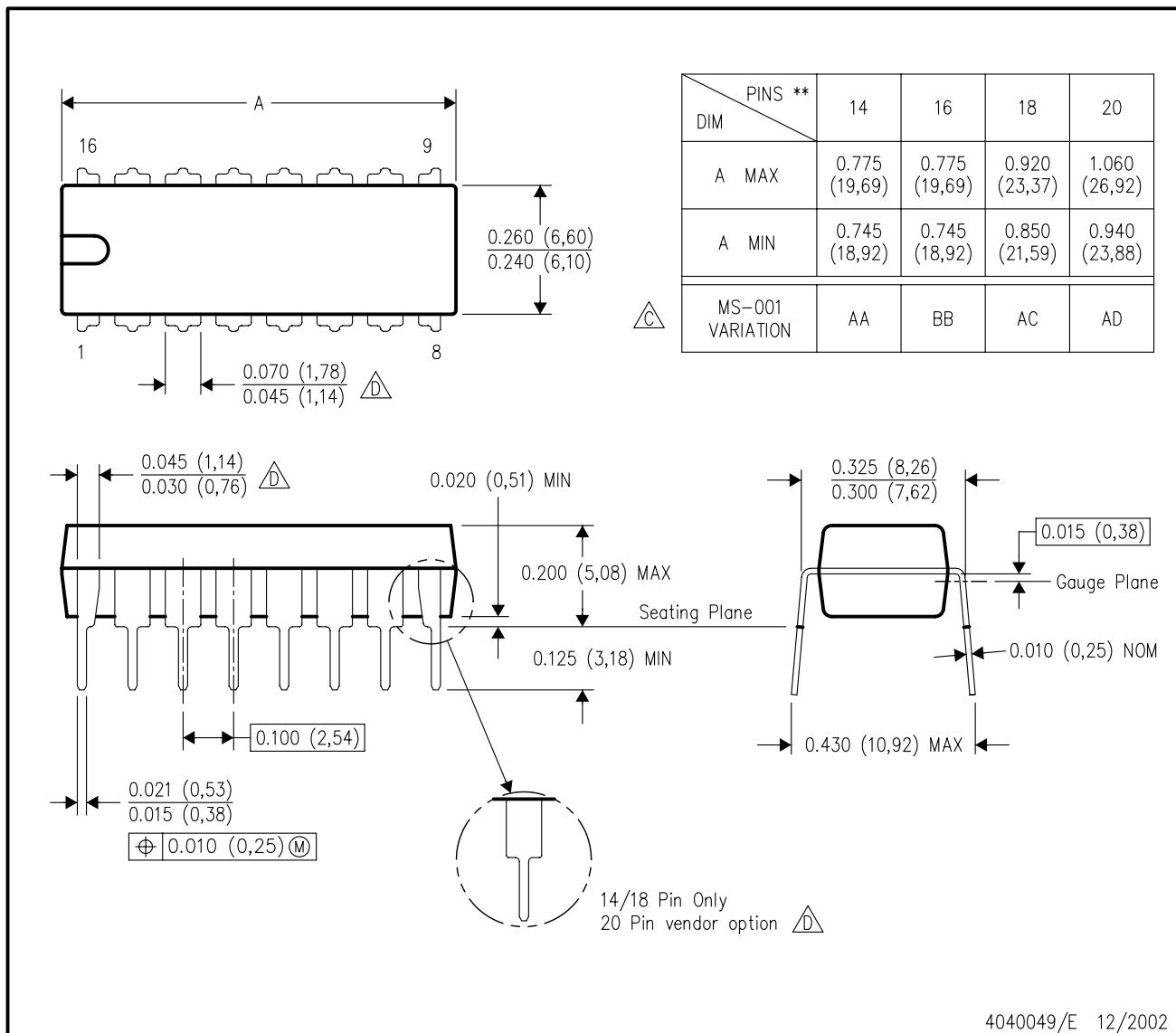
- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a metal lid.
- The terminals are gold plated.
- Falls within JEDEC MS-004

4040140/D 10/96

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

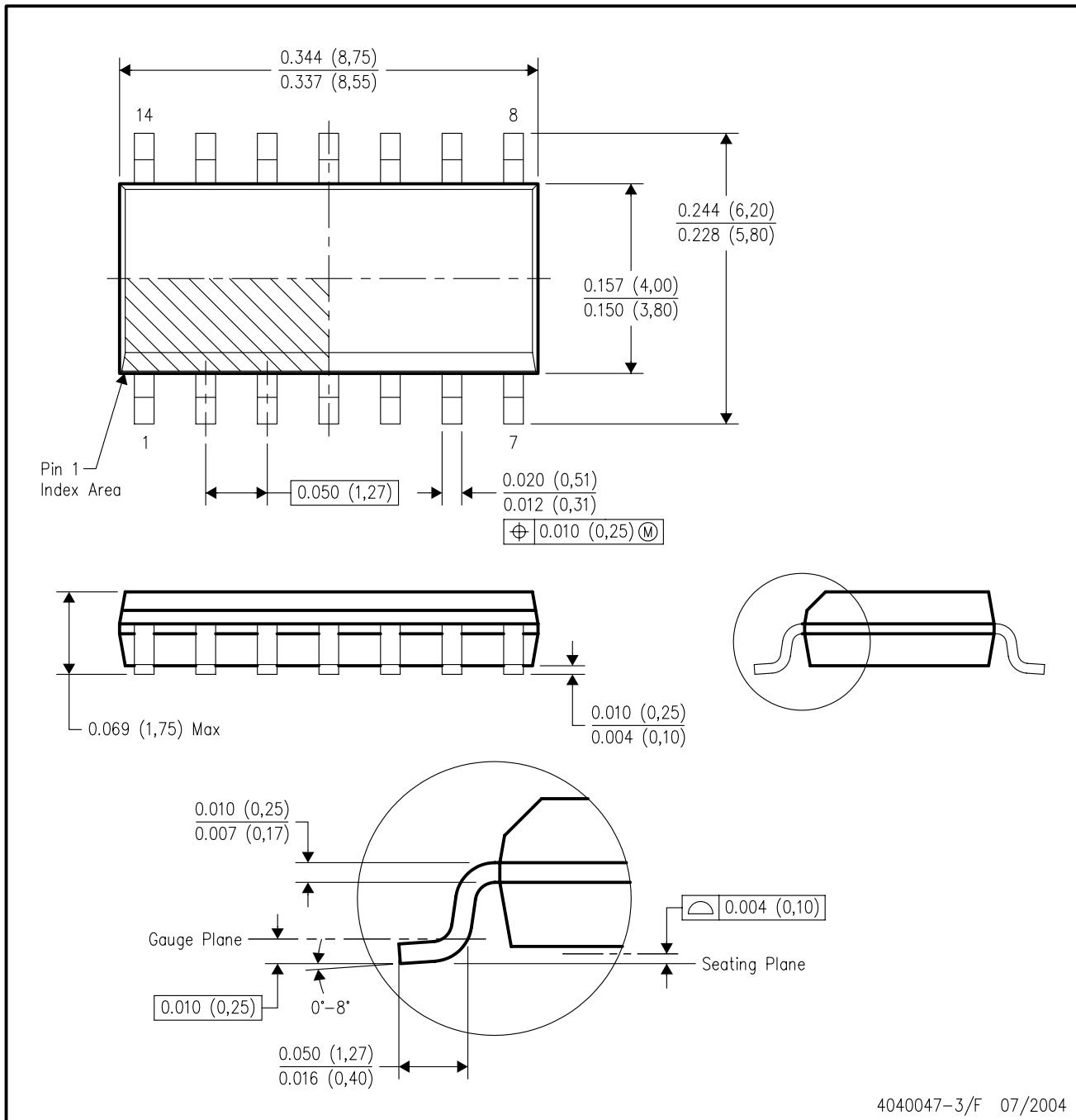
B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

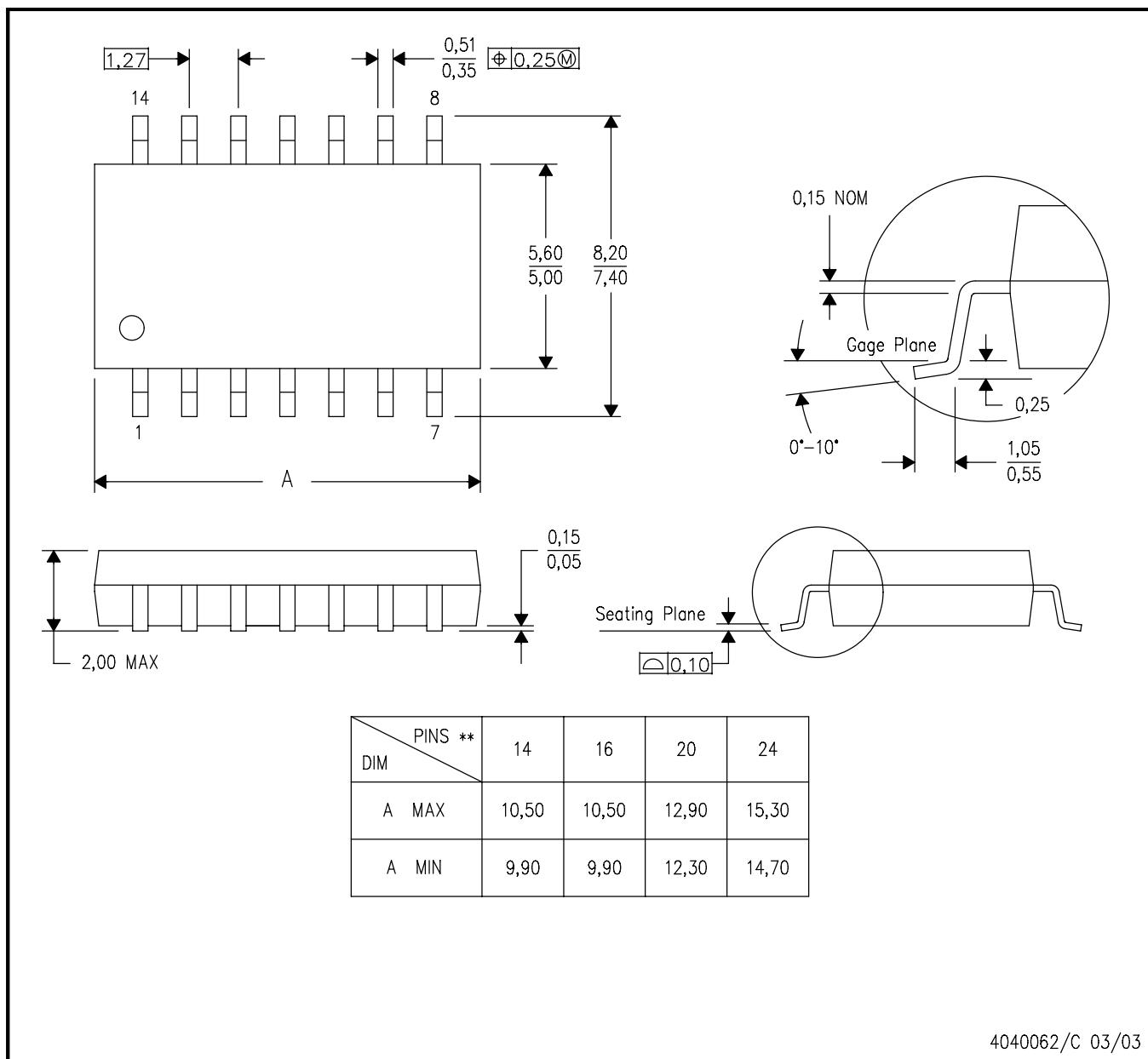
- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- Falls within JEDEC MS-012 variation AB.

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



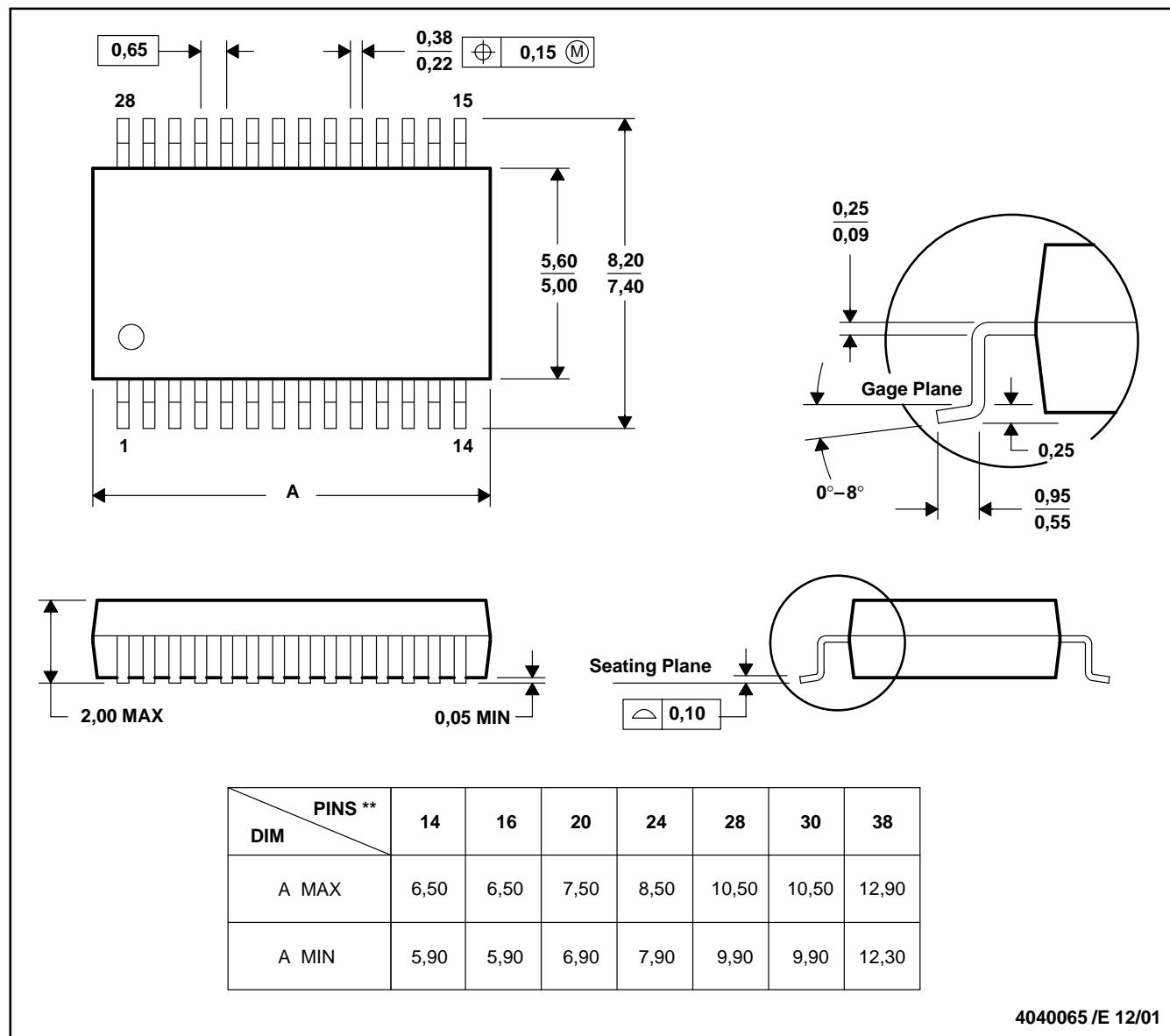
NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

4040062/C 03/03

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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